

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Michael Lenz	06/22/2006
Ricardo Eckert	06/20/2006
Gerrit Utz	06/21/2006
RECEIVING PARTY DATA	
Name:	Infineon Technologies AG
Street Address:	St.-Martin-Str. 53
City:	Munich
State/Country:	GERMANY
Postal Code:	81669
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11395104
CORRESPONDENCE DATA	
Fax Number:	(612)573-2005
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	612-573-2002
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Address Line 4:	Minneapolis, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	I433.216.101/13927
NAME OF SUBMITTER:	Steven E. Dicke
Total Attachments: 3	
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PATENT
REEL: 018005 FRAME: 0418

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ASSIGNMENT

For good and valuable consideration, I, Michael Lenz, a citizen of Germany, residing at Herzogplatz 50, 85604 Zorneding, Germany; Ricardo Eckert, a citizen of Germany, residing at Bocklinstrabe Harthausenstraße 36B, 83043 Bad Aibling, Germany; Gerritt Utz, a citizen of Germany, residing at Herzog-Ferdinand-Str. 5, 85456 Wartenberg, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation, organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and filed herewith, entitled:

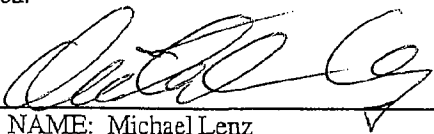
PROTECTION ARRANGEMENT FOR PROTECTING A POWER SEMICONDUCTOR COMPONENT AGAINST OVERCURRENT AND OVERTEMPERATURE

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: _____


NAME: Michael Lenz

DATE: _____

22.06.2006

SIGNATURE: _____

NAME: Ricardo Eckert

DATE: _____

SIGNATURE: _____

NAME: Gerritt Utz

DATE: _____

ASSIGNMENT

For good and valuable consideration, I, Michael Lenz, a citizen of Germany, residing at Herzogplatz 50, 85604 Zorneding, Germany; Ricardo Eckert, a citizen of Germany, residing at Bocklinstrabe Harthausenstraße 36B, 83043 Bad Aibling, Germany; Gerritt Utz, a citizen of Germany, residing at Herzog-Ferdinand-Str. 5, 85456 Wartenberg, Germany, hereinafter individually or collectively referred to as "Assignor";

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and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: _____ DATE: _____
NAME: Michael Lenz

SIGNATURE: Ricardo Eckert DATE: June 20 2006
NAME: Ricardo Eckert

SIGNATURE: _____ DATE: _____
NAME: Gerritt Utz

ASSIGNMENT

For good and valuable consideration, I, Michael Lenz, a citizen of Germany, residing at Herzogplatz 50, 85604 Zorneding, Germany; Ricardo Eckert, a citizen of Germany, residing at Bocklinstrabe Harthausenstraße 36B, 83043 Bad Aibling, Germany; Gerritt Utz, a citizen of Germany, residing at Herzog-Ferdinand-Str. 5, 85456 Wartenberg, Germany, hereinafter individually or collectively referred to as "Assignor";

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and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

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Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: _____ DATE: _____
NAME: Michael Lenz

SIGNATURE: _____ DATE: _____
NAME: Ricardo Eckert

SIGNATURE: Gerrit Utz DATE: 27/06/2006
NAME: ~~Gerritt Utz~~

Gerrit Utz

27/06/2006